Intelligent Power Module (IPM), 650 V, 30 A

NFAM3065L4B

General Description

The NFAM3065L4B is a fully-integrated inverter power module consisting of an independent High side gate driver, LVIC, six IGBT's and a temperature sensor (VTS), suitable for driving permanent magnet synchronous (PMSM) motors, brushless DC (BLDC) motors and AC asynchronous motors. The IGBT's are configured in a three-phase bridge with separate emitter connections for the lower legs for maximum flexibility in the choice of control algorithm.

The power stage has under voltage lockout protection (UVP). Internal boost diodes are provided for high side gate boost drive.

Features

- Three-phase 650 V, 30 A IGBT Module with Independent Drivers
- Active Logic Interface
- Built-in Undervoltage Protection (UVP)
- Integrated Bootstrap Diodes and Resistors
- Separate Low-side IGBT Emitter Connections for Individual Current Sensing of Each Phase
- Temperature Sensor (VTS)
- UL1557 Certified (File No.339285)
- This Device is Pb-Free and RoHS Compliant

Typical Applications

- Industrial Drives
- Industrial Pumps
- Industrial Fans
- Industrial Automation

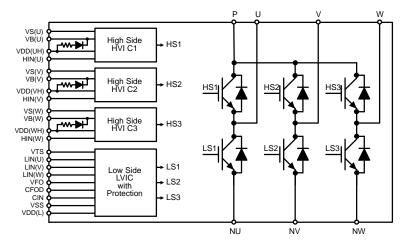
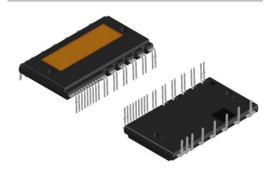


Figure 1. Application Schematic



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DIP39 54.5 x 31.0 CASE MODGX

MARKING DIAGRAM

O NFAM3065L4B O ZZZATYWW

Device marking is on package top side

NFAM3065L4B = Specific Device Code
ZZZ = Assembly Lot Code
A = Assembly Location
T = Test Location
Y = Year
WW = Work Week

ORDERING INFORMATION

| Device | Package | Shipping |
|-------------|-----------------------------------|----------|
| NFAM3065L4B | DIP39 54.5 x 31.0 (Pb-Free) | 90 / Box |

APPLICATION SCHEMATIC

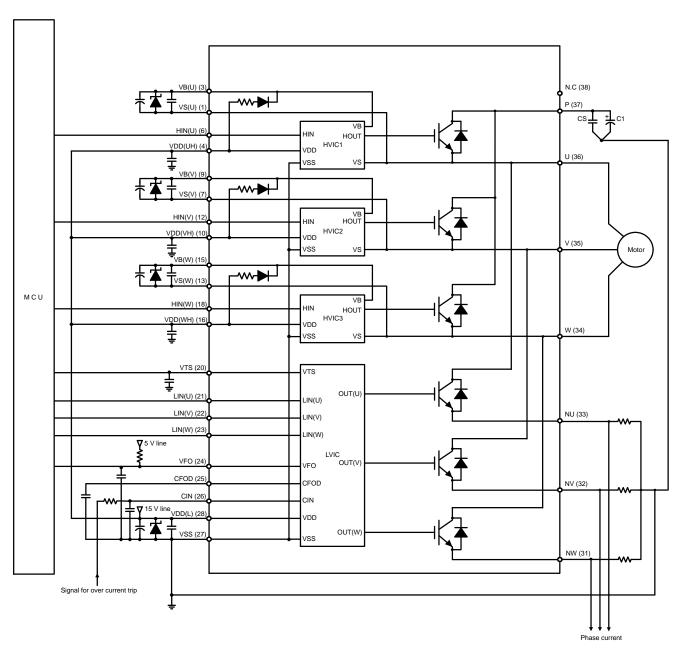


Figure 2. Application Schematic - Adjustable Option

BLOCK DIAGRAM

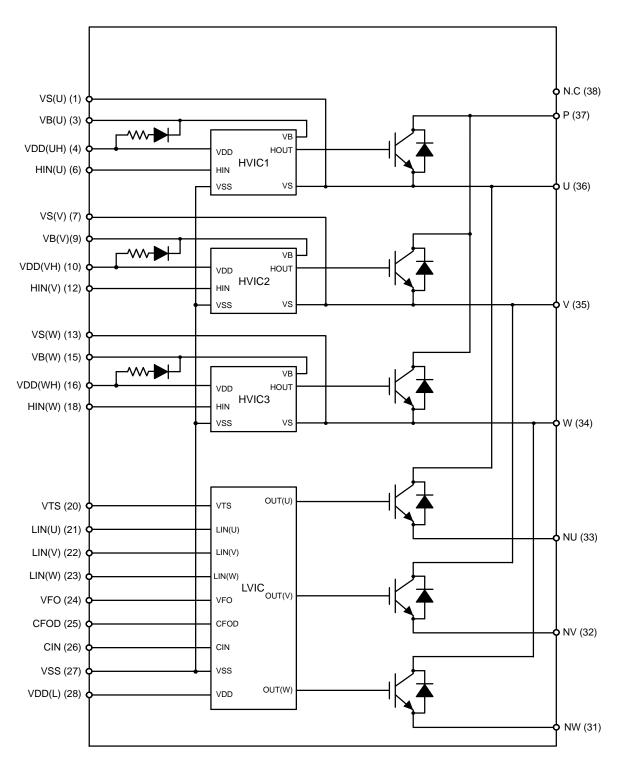


Figure 3. Equivalent Block Diagram

PIN FUNCTION DESCRIPTION

| Pin | Name | Description |
|------|---------|---|
| 1 | VS(U) | High-Side Bias Voltage GND for U phase IGBT Driving |
| (2) | _ | Dummy |
| 3 | VB(U) | High-Side Bias Voltage for U phase IGBT Driving |
| 4 | VDD(UH) | High-Side Bias Voltage for U phase IC |
| (5) | _ | Dummy |
| 6 | HIN(U) | Signal Input for High-Side U Phase |
| 7 | VS(V) | High-Side Bias Voltage GND for V phase IGBT Driving |
| (8) | - | Dummy |
| 9 | VB(V) | High-Side Bias Voltage for V phase IGBT Driving |
| 10 | VDD(VH) | High-Side Bias Voltage for V phase IC |
| (11) | - | Dummy |
| 12 | HIN(V) | Signal Input for High-Side V Phase |
| 13 | VS(W) | High-Side Bias Voltage GND for W phase IGBT Driving |
| (14) | - | Dummy |
| 15 | VB(W) | High-Side Bias Voltage for W phase IGBT Driving |
| 16 | VDD(WH) | High-Side Bias Voltage for W phase IC |
| (17) | - | Dummy |
| 18 | HIN(W) | Signal Input for High-Side W Phase |
| (19) | - | Dummy |
| 20 | VTS | Voltage Output for LVIC Temperature Sensing Unit |
| 21 | LIN(U) | Signal Input for Low-Side U Phase |
| 22 | LIN(V) | Signal Input for Low-Side V Phase |
| 23 | LIN(W) | Signal Input for Low-Side W Phase |
| 24 | VFO | Fault Output |
| 25 | CFOD | Capacitor for Fault Output Duration Selection |
| 26 | CIN | Input for Current Protection |
| 27 | VSS | Low-Side Common Supply Ground |
| 28 | VDD(L) | Low–Side Bias Voltage for IC and IGBTs Driving |
| (29) | - | Dummy |
| (30) | - | Dummy |
| 31 | NW | Negative DC-Link Input for U Phase |
| 32 | NV | Negative DC-Link Input for V Phase |
| 33 | NU | Negative DC-Link Input for W Phase |
| 34 | W | Output for U Phase |
| 35 | V | Output for V Phase |
| 36 | U | Output for W Phase |
| 37 | Р | Positive DC-Link Input |
| 38 | N.C | No Connection |
| (39) | - | Dummy |

Pins of () are the dummy for internal connection. These pins should be no connection.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C) (Note 2)

| Symbol | Rating | Conditions | Value | Unit |
|------------|--|---|-------------|-------|
| VPN | Supply Voltage | P–NU, NV, NW | 450 | V |
| VPN(surge) | Supply Voltage (Surge) | P-NU, NV, NW (Note 3) | 550 | V |
| VPN(PROT) | Self Protection Supply Voltage Limit (Short-Circuit Protection Capability) | VDD = VBS = 13.5 V ~ 16.5 V, Tj = 150°C, VCES < 650 V, Non-Repetitive, < 2 µs | 400 | V |
| Vces | Collector-emitter voltage | | 650 | V |
| VRRM | Maximum Repetitive Revers Voltage | | 650 | V |
| ±lc | Each IGBT Collector Current | | ±30 | Α |
| ±lcp | Each IGBT Collector Current (Peak) | Under 1 ms Pulse Width | ±60 | Α |
| VDD | Control Supply Voltage | VDD(UH,VH,WH), VDD(L)-VSS | -0.3 to 20 | V |
| VBS | High-Side Control Bias Voltage | VB(U)-VS(U), VB(V)-VS(V), VB(W)-VS(W) | -0.3 to 20 | V |
| VIN | Input Signal Voltage | HIN(U), HIN(V), HIN(W), LIN(U), LIN(V), LIN(W)-VSS | -0.3 to VDD | V |
| VFO | Fault Output Supply Voltage | VFO-VSS | -0.3 to VDD | V |
| IFO | Fault Output Current | Sink Current at VFO pin | 2 | mA |
| VCIN | Current Sensing Input Voltage | CIN-VSS | -0.3 to VDD | V |
| Pc | Corrector Dissipation | Per One Chip | 113 | W |
| Tj | Operating Junction Temperature | | -40 to +150 | °C |
| Tstg | Storage temperature | | -40 to +125 | °C |
| Tc | Module Case Operation Temperature | | -40 to +125 | °C |
| Viso | Isolation voltage | 60 Hz, Sinusoidal, AC 1 minute, Connection Pins to Heat Sink Plate | 2500 | V rms |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

| Symbol | Rating | Conditions | Min | Тур | Max | Unit |
|-----------------------|------------|-------------------------------------|-----|-----|-----|------|
| R _{th(j-c)Q} | | Inverter IGBT Part (per 1/6 module) | - | - | 1.1 | °C/W |
| $R_{th(j-c)F}$ | Resistance | Inverter FWD Part (per 1/6 module) | - | 1 | 2.2 | °C/W |

^{4.} Refer to <u>ELECTRICAL CHARACTERISTICS</u>, <u>RECOMMENDED OPERATING RANGES</u> and/or APPLICATION INFORMATION for Safe Operating parameters.

^{2.} Refer to <u>ELECTRICAL CHĂRACTERISTICS</u>, <u>RECOMMENDED OPERATING RANGES</u> and/or APPLICATION INFORMATION for Safe Operating parameters.

^{3.} This surge voltage developed by the switching operation due to the wiring inductance between P and NU, NV, NW terminal.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Rating | Cond | Min | Тур | Max | Unit | |
|-------------------------|--------------------------------|---|--------------------------------|------------|------|------|-------|
| VPN | Supply Voltage | P-NU, NV, NW | | - | 300 | 400 | V |
| VDD | Gate Driver Supply | VDD(UH,VH,WH) | , VDD(L)-VSS | 13.5 | 15 | 16.5 | V |
| VBS | - Voltages | VB(U)-VS(U), VB VB(W)-VS(W) | 13.0 | 15 | 18.5 | V | |
| dVDD / dt, dVBS / dt | Supply Voltage Variation | | | – 1 | - | 1 | V/µs |
| fPWM | PWM Frequency | | | 1 | _ | 20 | kHz |
| DT | Dead Time | Turn-off to Turn-or | Turn-off to Turn-on (external) | | _ | - | μS |
| lo | Allowable r.m.s. Current | VPN = 300 V, VDD = 15 V, P.F. = 0.8 | f _{PWM} = 5 kHz | _ | - | 25.7 | A rms |
| | | Tc ≤ 125°C, Tj ≤ 150°C (Note 5) | f _{PWM} = 15 kHz | - | - | 18.8 | |
| PWIN (on) | Allowable Input Pulse Width | 200 V ≤ VPN ≤ 400 V 13.5 V ≤ VDD ≤ 16.5 V 13.0 V ≤ VBS ≤ 18.5 V -20°C ≤ Tc ≤ 100°C | | 1.0 | - | - | μS |
| PWIN (off) |] | | | 1.5 | - | - |] |
| | Package Mounting Torque | M3 type screw | | 0.6 | 0.7 | 0.9 | Nm |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

5. Allowable r.m.s current depends on the actual conditions.

6. Flatness tolerance of the heatsink should be within –50 µm to +100 µm.

ELECTRICAL CHARACTERISTICS (Tc = 25°C, VDD = 15 V, VBS = 15 V, unless otherwise specified.) (Note 7)

| Symbol | Parameter | | Test Conditions | Min | Тур | Max | Unit |
|-------------|---|--------------------------------|--|------|------|------|------|
| INVERTER SE | CTION | | | | | | |
| Ices | Collector–Emitter Leakage | | Vce = Vces , Tj = 25°C | _ | _ | 1 | mA |
| | Current | | Vce = Vces, Tj = 150°C | _ | _ | 10 | mA |
| VCE(sat) | /CE(sat) Collector–Emitter Saturation Voltage | | VDD = VBS = 15 V, IN = 5 V Ic = 30 A, Tj = 25°C | - | 1.60 | 2.30 | V |
| | | | VDD = VBS = 15 V, IN = 5 V Ic = 30 A, Tj = 150°C | - | 1.80 | - | V |
| VF | FWDi Forward Voltage | IN = 0 V, If = 30 A, Tj = 25°C | - | 2.00 | 2.40 | V | |
| | | | IN = 0 V, If = 30 A, Tj = 150°C | - | 2.00 | - | V |
| ton | High side | Switching | witching mes | 0.80 | 1.25 | 1.85 | μS |
| tc(on) | 7 | rimes | | _ | 0.25 | 0.65 | μS |
| toff | 7 | | | _ | 1.60 | 2.20 | μS |
| tc (off) | 7 | | | _ | 0.25 | 0.75 | μS |
| trr | 7 | | | _ | 0.15 | - | μS |
| ton | Low side | | | 0.80 | 1.40 | 2.00 | μS |
| tc(on) | 7 | Times | mes $Ic = 30 \text{ A}, Tj = 25^{\circ}\text{C}, IN = 0 \Leftrightarrow 5 \text{ V}$ Inductive Load | _ | 0.25 | 0.55 | μS |
| toff | 7 | | | _ | 1.60 | 2.20 | μS |
| tc(off) | 7 | | | _ | 0.25 | 0.75 | μS |
| trr | 1 | | | _ | 0.10 | - | μS |

ELECTRICAL CHARACTERISTICS (Tc = 25°C, VDD = 15 V, VBS = 15 V, unless otherwise specified.) (Note 7) (continued)

| Symbol | Parameter | Test Condition | Min | Тур | Max | Unit | | |
|------------------|---|---|---|-------|-------|-------|----|--|
| DRIVER SECTION | | | | | | | | |
| IQDDH | Quiescent VDD Supply Current | VDD(UH,VH,WH) = 15 V, HIN(U,V,W) = 0 V | VDD(UH)-VSS VDD(VH)-VSS VDD(WH)-VSS | - | - | 0.30 | mA | |
| IQDDL | | VDD(L) = 15 V, LIN(U,V,W) = 0 V | VDD(L)-VSS | - | _ | 3.50 | mA | |
| IPDDH | Operating VDD Supply Current | VDD(UH,VH,WH) = 15 V, fPWM = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for High–Side | VDD(UH)-VSS VDD(VH)-VSS VDD(WH)-VSS | - | - | 0.40 | mA | |
| IPDDL | | VDD(L) = 15 V, fPWM = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for Low–Side | VDD(L)-VSS | - | - | 6.00 | mA | |
| IQBS | Quiescent VBS Supply Current | VBS = 15 V, HIN(U,V,W) = 0 V | VB(U)-VS(U) VB(V)-VS(V) VB(W)-VS(W) | - | - | 0.30 | mA | |
| IPBS | Operating VBS Supply Current | VDD = VBS = 15 V, fPWM = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for High–Side | VB(U)-VS(U) VB(V)-VS(V) VB(W)-VS(W) | - | - | 5.00 | mA | |
| VIN(ON) | ON Threshold voltage | HIN(U,V,W)-VSS, LIN(U,V,W) | _ | _ | 2.6 | V | | |
| VIN(OFF) | OFF Threshold voltage | 1 | | 0.8 | - | - | V | |
| VCIN(ref) | Short Circuit Trip Level | VDD = 15 V, CIN-VSS | | 0.46 | 0.48 | 0.50 | V | |
| UVDDD | Supply Circuit | Detection Level | | 10.3 | - | 12.5 | V | |
| UVDDR | Under-Voltage Protection | Reset Level | | 10.8 | - | 13.0 | V | |
| UVBSD | | Detection Level | | 10.0 | - | 12.0 | V | |
| UVBSR | | Reset Level | | 10.5 | - | 12.5 | V | |
| VTS | Voltage Output for LVIC Temperature Sensing Unit | VTS-VSS = 10 nF, Temp. = 2 | 5°C | 0.905 | 1.030 | 1.155 | V | |
| VFOH | Fault Output Voltage | VDD = 0 V, CIN = 0 V, VFO Circuit: 10 k Ω to 5 V Pull-up | | 4.9 | _ | _ | V | |
| VFOL |] | VDD = 0 V, CIN = 1 V, VFO Circuit: 10 kΩ to 5 V Pul | - | - | 0.95 | V | | |
| t _{FOD} | Fault-Output Pulse Width | CFOD = 22 nF | 1.6 | 2.4 | - | ms | | |
| OOTSTRAP | SECTION | | | | | | | |
| VF | Bootstrap Diode Forward Voltage | If = 0.1 A | 3.4 | 4.6 | 5.8 | V | | |
| RBOOT | Built-in Limiting Resistance | | | 30 | 38 | 46 | Ω | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

7. Performance guaranteed over the indicated operating temperature range by design and/or characterization tested at T_J = T_A = 25°C. Low

duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.

^{8.} The fault-out pulse width t_{FOD} depends on the capacitance value of CFOD according to the following approximate equation: t_{FOD} = 0.1 × 10⁶ × CFOD (s).

9. Values based on design and/or characterization.

Temperature of LVIC versus VTS Characteristics

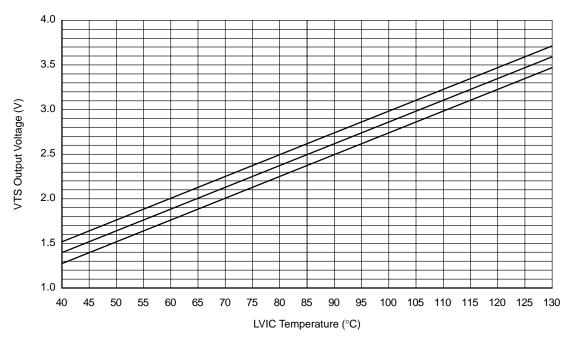


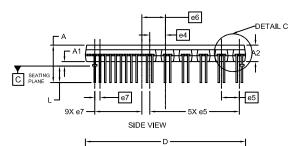
Figure 4. Temperature of LVIC versus VTS Characteristics

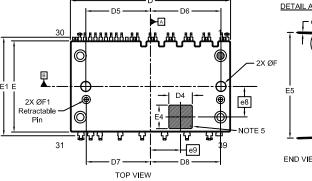


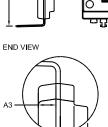
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DATE 02 APR 2019

| | M | ILLIMETER | RS | | MILLIMETERS | | |
|-------------|-------|-----------|-------|-----|----------------|-----------|-------|
| DIM | MIN. | NOM. | MAX. | DIM | MIN. | MAX. | |
| Α | 12.20 | 12.7 | 13.2 | Е | 30.90 | 31.00 | 31.10 |
| A1 | 1.00 | 1.50 | 2.00 | E1 | | 33,50 REF | |
| A2 | 5.50 | 5.60 | 5.70 | E2 | | 26.14 REF | |
| A3 | | 2,00 REF | | E3 | | 12,35 REF | |
| A4 | | 1.55 REF | | E4 | | 8.00 REF | |
| A5 | | 3.10 REF | | E5 | 35.40 | 35.90 | 36.40 |
| b | 0.90 | 1.00 | 1.10 | е | 2.81 REF | | |
| b1 | 1.90 | 2.00 | 2.10 | e1 | 7.62 BSC | | |
| b2 | 0.40 | 0.50 | 0.60 | e2 | | 6.60 BSC | |
| b3 | 1.40 | 1.50 | 1.60 | e3 | 3.30 BSC | | |
| С | | 0.50 REF | | e4 | 5.35 REF | | |
| D | 54.40 | 54.50 | 54.60 | e5 | | 6.10 BSC | |
| D3 | | 39.25 REF | | e6 | | 8.02 REF | |
| D4 | | 8.00 REF | | e7 | | 1.78 BSC | |
| D5 | | 22.00 REF | | e8 | | 10.35 REF | |
| D6 | | 24.00 REF | | e9 | 10.25 REF | | |
| D7 | | 21.85 REF | | e10 | 3.60 REF | | |
| D8 | | 23.85 REF | | e11 | 1.00 REF | | |
| | | | | e12 | | 0.89 BSC | |
| | | | | F | 3.20 | 3.30 | 3.40 |
| — D3 | | \neg | | F1 | 1.40 1.50 1.60 | | |





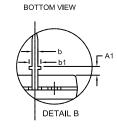


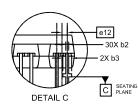
DETAIL A

-DETAIL B

 \mathbf{e}

e11





E2

EXPOSED CU AREA

5.60 REF

NOTES:

2X e3

1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.

SIDE VIEW

- ASME Y14.5M, 2009.
 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSION b and c APPLY TO THE PLATED LEADS AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP.
- 4. POSITION OF THE LEAD IS DETERMINED AT THE BASE OF THE LEAD WHERE IT EXITS THE PACKAGE BODY.

4X e1

e1

- 5. AREA FOR 2D BAR CODE.
- 6. SHORTENED/CUT PINS ARE 2,5,8,11,14,17,19,29, 30 AND 39.

GENERIC MARKING DIAGRAM*

e10

XXXXX = Specific Device Code
ZZZ = Assembly Lot Code
AT = Assembly & Test Location

Y = Year WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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